●技術論文

「エレクトロニクス実装学会誌」7〔3〕266~270 (2004)

ワイヤ流れに及ぼす封止用樹脂内フィラ粒度分布の影響

大見謝　和人*，高堂　積**，大野　恭秀***

Effect of Filler Size Distribution in Molding Compounds on Wire Sweep

Kazuto OMISHA*, Tsumoru TAKADO** and Yasuhide OHNO***

*熊本大学大学院自然科学研究科（〒860-8555　熊本県熊本市黒髪2-39-1）
**NEC九州（〒861-4113　熊本県熊本市八幡1-1-1）
***熊本大学工学部（〒860-8555　熊本県熊本市黒髪2-39-1）
*Graduate School of Science, Kumamoto University (2-39-1 Kurokami, Kumamoto-shi, Kumamoto 860-8555)
**NEC Kyusyu (1-1-1 Yahata, Kumamoto-shi, Kumamoto 861-4113)
***Faculty of Engineering, Kumamoto University (2-39-1 Kurokami, Kumamoto-shi, Kumamoto 860-8555)

Abstract

Plastic package has mainly been used in current IC package, and transfer mold is the mainstream of the molding technology. When high viscous mold resin flow into mold cavity during filling stage, bonded Au wire connected between chip and lead frame usually deform. This deformation is called 'wire sweep'. Excessive wire sweep may cause defects such as electric short at semiconductor chip and wire. This paper describes effect of filler profiles involved mold resin on wire sweep.

Key Words: *Wire Sweep, Mold Resin, Fiiler*